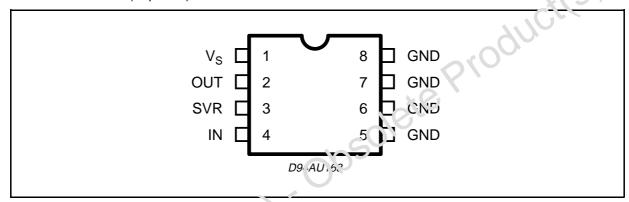
## **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
$V_S$	Operating Supply Voltage	18	V
Ιο	Output Put Peak Current	1.5	Α
T <sub>op</sub>	Operating Temperature Range	0 to 70	°C
Tj	Junction Temperature	150	°C
T <sub>stq</sub>	Storage Temperature Range	-40 to 125	°C

# PIN CONNECTION (Top view)



## **THERMAL DATA**

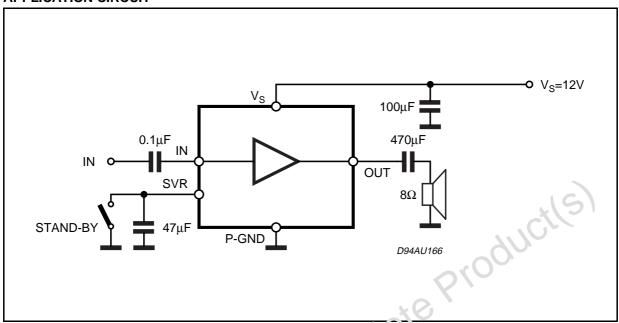
Symbol	Parameter	Value	Unit
R <sub>th j-amb</sub>	Thermal Resistance Junction to ambient (on PCB)	80	°C/W
R <sub>th j-case</sub>	Thermal Resistance Junction to case	15	°C/W

# **ELECTRICAL CHARACTERISTICS** (T<sub>amb</sub> = 25°C; V<sub>S</sub> = 12V; R<sub>L</sub> = 8 $\Omega$ ; f = 1KHz; unless otherwise specified.)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
Vs	Supply Voltage Range		4.5		18	V
Is	Quiescent Current			20	30	mA
I <sub>sb</sub>	Stand-By Current	Pin 3 shorted to GND			0.3	mA
Vo	Quiescent Output Voltage			6		V
A <sub>V</sub>	Voltage Gain			32		dB
R <sub>IN</sub>	Input Impedance			100		ΚΩ
Po	Output Power	THD = 10%	1.8	2		W
THD	Distortion	$P_O = 1W$			1.0	%
SVR	Supply Voltage Rejection	$V_{ripple}$ = 150mVrms; $F_{ripple}$ = 1KHz		50		dB
Eı	Input Noise Voltage	Rg = $10K\Omega$ ; BW = $20Hz$ to $20KHz$		1.5	5	μV
$V_{sb}$	Stand-By Enable Voltage				1	V

<u> 577</u>

### **APPLICATION CIRCUIT**



### **APPLICATION HINTS:**

For 12V supply and  $8\Omega$  speaker application, its maximum power dissipation is about 1W.

Assumming that max ambient temperature is 70°C. Required thermal resistance of the device and heat dissipating means must be equal to (150 - 70)/1 = 80°C/W.

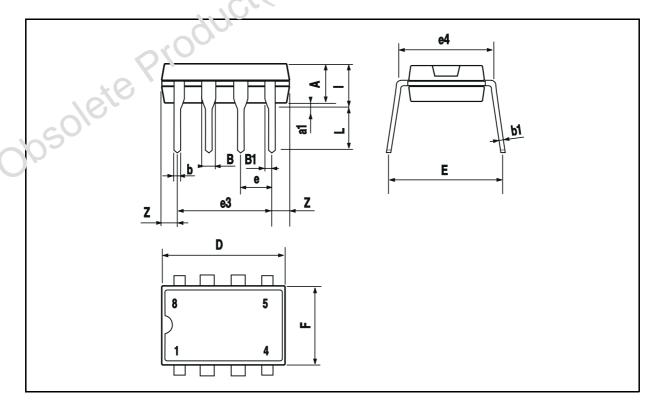
Junction to pin thermal resistance of the package is about 15°C/W. That means external heat sink of about 65°C/W is required.

Cu ground plane of PCB can be used as heat dissipating means.

Stand-By switches must be able to discharge  $C_{\mbox{\scriptsize svr}}$  current.

# MINIDIP PACKAGE MECHANICAL DATA

DIM.	mm			inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Α		3.3			0.130		
a1	0.7			0.028			
В	1.39		1.65	0.055		0.065	
B1	0.91		1.04	0.036		0.041	
b		0.5			0.020		
b1	0.38		0.5	0.015		0.020	
D			9.8			0.386	
E		8.8			0.345		
е		2.54			L 100		
e3		7.62			0.300		
e4		7.62		10:10	0.300		
F			7.1	0/0		0.280	
I			7.0			0.189	
L		3.3			0.130		
Z	0.44		1.6	0.017		0.063	



4/5



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57

5/5